

CLR[®] has excellent printability. In order to increase joint reliability, even with thicker stencil, enough solder paste can be printed for fine pitch.

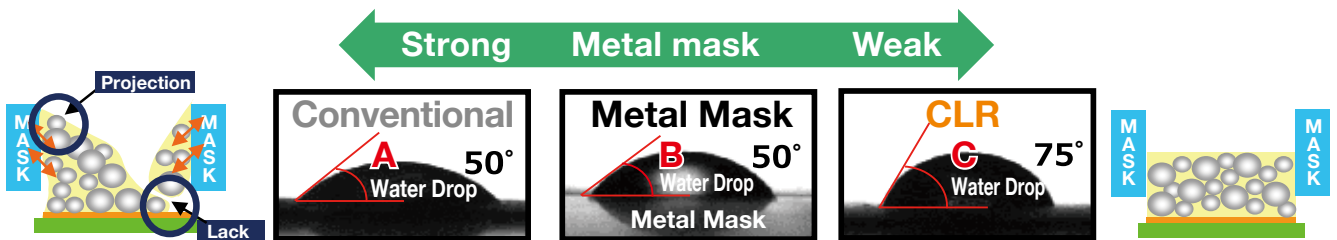
Characteristics

- To improve printability, new synthetic resin with enhanced water repellency is developed
- With mask thickness 150 μ m, stable printing is possible for 0.4mmQFP & 0.5mmBGA
- Excellent printability is achieved even at high speed printing (~100mm/sec)
- Resistance to flux residue crack (-40 \leftrightarrow 125 $^{\circ}$ C, 2,000 cycle)

Printability

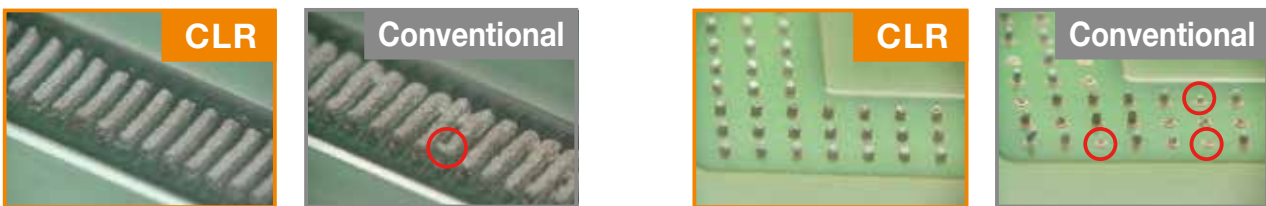
Mechanism for improved printing performance

- Less friction with metal mask opening, and as a result, fine pitch printing improved
- Adding water repellent material improved electrical reliability



Printing Mask thickness :150 μ m

- 0.4mmQFP • 0.5mmBGA mounting is possible with 150 μ m mask
- 0.4mm Pitch QFP
- 0.5mm Pitch BGA



High Speed Printing Mask thickness :150 μ m Opening : Φ 0.275mm

- Maintain excellent printing at high speed printing (100mm/sec)

